



Press Release

UNISEM ENDS 2010 WITH NET PROFIT OF RM182.96 MILLION ON RM1.395 BILLION REVENUE

Kuala Lumpur, 24 February 2011 – Unisem (M) Berhad today announced its fourth quarter (**4Q10**) and full year results ended 31 December 2010 (**FY2010**).

The Group recorded revenue of RM1.395 billion for FY2010, a 34.6% increase from 2009. Group net profit grew 3 folds to RM182.96 million for FY2010, from RM60.75 million recorded in 2009. The significant increase in revenue and net profit in 2010 was attributable to improved sales volume from a broad-based demand for our services with notable surge in the demand for our wafer bumping and advanced packaging services.

For Q410, Group revenue increased 5.9% to RM335.6 million from RM316.8 million achieved in the same quarter a year ago (**4Q09**). Profit before taxation grew 6.1% to RM38.8 million from RM36.5 million in 4Q09. Net profit for 4Q10 increased 19.5% to RM41.7 million from RM34.9 million in 4Q09.

As compared to the prior quarter (**3Q10**) the Group revenue and net profit decline 9.5% and 21% from RM370.7 million and RM51.9 million respectively in 3Q10. The decline in revenue and net profit in 4Q10 was mainly due to lower sales volume as a result of inventory adjustment in the industry.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 4Q10 came in at RM81.1 million; EBITDA margin was about 24% for 4Q10. Group EBITDA for 2010 increased 48% to RM361.9 million from RM244.2 million achieved in 2009.

Equipment capacity utilization averaged at about 84% for the group in 4Q10. Group capital expenditure incurred in 4Q10 was about RM98.5 million, principally for purchase of assembly and final test equipment for Unisem (M) Berhad and Unisem Chengdu.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "The Group anticipates a decline in revenue and earnings in the first quarter due to seasonal softening and residual inventory adjustments from the previous quarter; however, the directors expect further growth in the business of the Group for the financial year 2011."

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 10,000 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.